No.P-JAE-E009/1 DATE 2025-11

PRODUCTS DATA SHEET

MICRO FUSE

Type JAE

Size 3216

UL/cUL approved File No. E170721 ROHS COMPLIANT LEAD FREE





Granted Patents

Japanese patent (No.4200450)



MATSUO ELECTRIC CO., LTD.

Type JAE

Type JAE micro fuse is designed for circuit protection against excessive current in portable electronic equipment, electric circuit around battery, etc. because the demand for high capacity batteries is increasing.

Wire material is adopted for fuse element, and the performance against rush current is increased in spite of compact design. Also, the ecology design of Type JAE is environmentally friendly because of complete lead-free.

FEATURES

- 1. Our original construction design has excellent fusing and cutting characteristics.
- 2. Especially, performance against rush current is excellent since wire material is used for fuse element.
- 3. Surface temperature rise is 75°C or less when applying rated current for fusing. This gives less influence to the peripheral units.
- 4. Resistance to soldering heat: Reflow or flow soldering 10 seconds at 260°C
- 5. Our original terminal construction makes almost no occurrence of Tombstone phenomenon.
- 6. Small size of 3216 (3.2 × 1.6 × 1.4 mm)
- 7. Suitable for automatic mounting
- 8. Precise dimensions allows high-density mounting and symmetrical construction of terminals provide "Self-Alignment".
- 9. Complete lead-free, bromine-free.

APPLICATION CLASSIFICATION BY USE

The application classification by use which divided the market and use into four is set up supposing our products being used for a broad use.

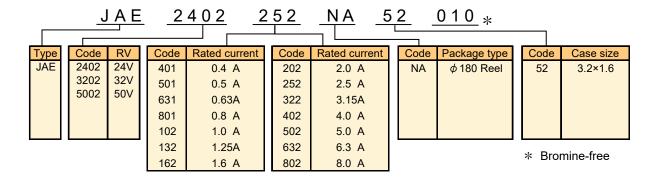
Please confirm the application classification by use of each product that you intend to use.

Moreover, please be sure to inform to our Sales Department in advance in examination of the use of those other than the indicated use.

RATING

Item	Rating
Category Temperature Range	-40 ~+125℃
Rated Current	0.4-0.5-0.63-0.8-1.0-1.25-1.6-2.0-2.5-3.15-4-5-6.3-8A
Rated Voltage	24VDC
Voltage Drop	Refer to CATALOG NUMBERS AND RATING
Insulation Resistance (between terminals and case)	1000 MΩ or more
Fusing Characteristics	Fusing within 2 minute if the current is 250% of rated current.
Clearing Characteristics	Breaking voltage : 24 V, 32V, 50V
Cleaning Characteristics	Breaking current : 50 A

ORDERING INFORMATION



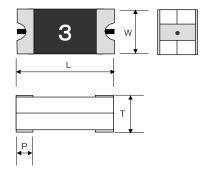
CATALOG NUMBERS AND RATING

Oct., 2022

Catalog number	Case size	Rated current A	Internal resistance mΩ (Typical)	Voltage drop mV (Max.)	Rated voltage VDC	Breaking current A	
JAE 2402 401 □□52010		0.4	310	220			
JAE 2402 501 □□52010		0.5	240	200			
JAE 2402 631 □□52010		0.63	190	150			
JAE 2402 801 □□52010		0.8	145	150			
JAE 2402 102 □□52010	3.2×1.6	1.0	112	150	24	50	
JAE 2402 132 □□52010		1.25	87	150	24		
JAE 2402 162 □□52010		1.6	70	150			
JAE 2402 202 □□52010		2.0	54	150			
JAE 2402 252 □□52010		2.5	43	150			
JAE 2402 322 □□52010		3.15	34	150			
JAE 3202 402 □□52010		4.0	11.6	150			
JAE 3202 502 □□52010	3.2×1.6	5.0	9.16	150	32	50	
JAE 3202 632 □□52010	3.2^1.0	6.3	7.17	150	32	30	
JAE 3202 802 □□52010		8.0	5.96	150			
JAE 5002 402 □□52010		4.0	11.6	150			
JAE 5002 502 □□52010	3.2×1.6	5.0	9.16	150	50	50	
JAE 5002 632 □□52010	3.2^1.0	6.3	7.17	150		30	
JAE 5002 802 □□52010		8.0	5.96	150			

For the taping type, the packing code "NA" will be entered in $\Box\Box$. Catalog numbers are approved by UL and cUL. (File No.E170721)

DIMENSIONS



Main body : Glass epoxy Terminal : Tin plating

 Terminal : Tin plating
 (mm)

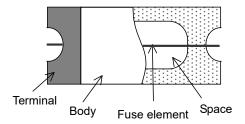
 Case size
 Case code
 L
 W
 T
 P

 3216
 52
 3.2 ± 0.2
 1.6 ± 0.2
 1.4 ± 0.2
 0.6 ± 0.2

MARKING

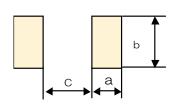
Code : Rated current	Code : Rated current	Code: Rated current
S : 0.40A	W : 1.25A	4 : 4.00A
T : 0.50A	X : 1.60A	5 : 5.00A
U : 0.63A	2 : 2.00A	6 : 6.300A
V : 0.80A	Y : 2.50A	8 : 8.00A
1 : 1.00A	3 : 3.15A	

CONSTRUCTION



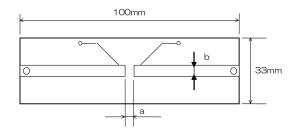
Name	Material, standard, and treatment
Fuse element	Lead-free alloy
Space	_
Terminal	Tin plating
Body	Glass epoxy

RECOMMENDED PAD DIMENSIONS



	(mm)		
	Size 3216		
а	1.0		
b	1.6		
С	1.6		
(Reflow)			

STANDARD TEST BODY



Glass epoxy body on one side Board thickness: 1.6mm

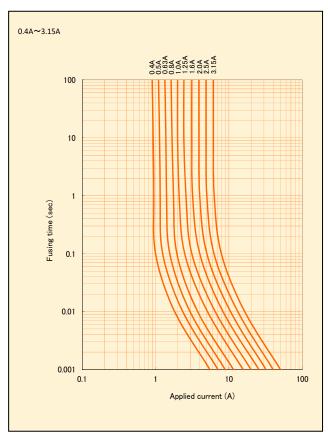
	Less than 4A	More than 4A
а	1.5mm	1.4mm
b	5mm	10mm
Copper layer	35µm	70µm

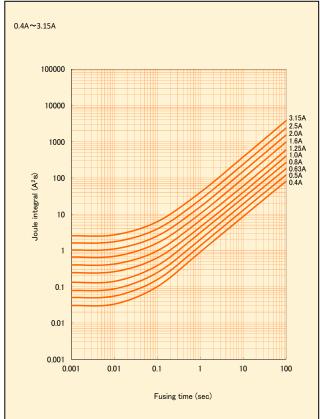
PERFORMANCE

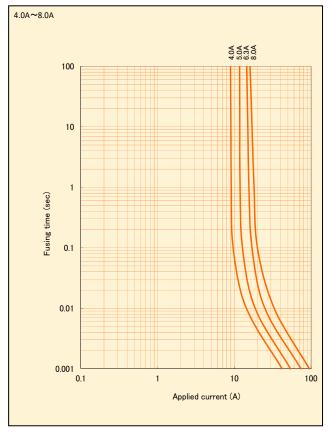
No.	Item	Performance	Test method
1	Temperature rise	Temperature rise shall not exceed 75°C.	Apply rated current.
2	Current-carrying capacity	Shall not open within 1 hour.	Apply 100% of rated current.
3	Clearing characteristics	Arc shall not be continued. Marking shall be legible.	Breaking voltage : 24V Breaking current : 50 A
4	Voltage drop	Voltage drop is below the value specified in CATALOG NUMBERS AND RATING.	Apply rated current.
5	Fusing characteristics	Fusing within 2 min.	Apply 250% of rated current. (Ambient temperature : 10 ~ 30°C)
6	Insulation resistance	1000 MΩ or more	Insulation resistance between terminals and case
7	Electrode strength (Bending)	No mechanical damage. Resistance change after the test shall be within $\pm20\%$.	Board supporting width : 90 mm Bending speed : Approx. 0.5 mm/sec. Duration : 5 sec. Bending : 3 mm
8	Shear test	No mechanical damage. Resistance change after the test shall be within \pm 20%.	Applied force : 20 N (2.04 kgf) Duration : 10 sec. Tool : R0.5 Direction of the press : side face
9	Substrate bending test	No mechanical damage. Resistance change after the test shall be within $\pm20\%$.	Supporting dimension : 1.6 mm Applied force : 20 N (2.04 kgf) Duration : 10 sec. Tool : R0.5 Direction of the press : thickness direction of product
10	Solderability (Solder Wetting time)	Solder Wetting time : within 3sec.	Solder: Sn-3Ag-0.5Cu Temperature: 245 ± 3°C meniscograph method Solder: JISZ3282 H60A, H60S, H63A Temperature: 230 ± 2°C meniscograph method
11	Solderability (new uniform coating of solder)	The dipping surface of the terminals shall be covered more than 95% with new solder.	Solder: Sn-3Ag-0.5Cu Temperature: 245 ± 3°C Dipping: 3 sec. Solder: JISZ3282 H60A, H60S, H63A Temperature: 230 ± 2°C Dipping: 3 sec.
12	Resistance to soldering heat	Marking shall be legible. No mechanical damage. Resistance change after the test shall be within $\pm20\%$.	Dipping (1 cycle) Preconditioning: 100 ~ 150°C, 30±5 sec. Temperature: 260 ± 3°C, 5 ½ sec. Reflow soldering (2 cycles) Preconditioning: 150~180°C, 90±30 sec. Peak: 250½°C Holding: 230°C or higher, 30±10 sec. Cooling: 3 ~ 6°C/sec or faster Manual soldering Temperature: 350 ± 10°C Duration: 2 ~ 3 sec Measure after 1 hour left under room temperature and humidity.
13	Solvent resistance	Marking shall be legible. No mechanical damage. No significant irregularity in the appearance.	Dipping rinse Solvent : Isopropyl alcohol Duration : 90 sec.
14	Vibration	No mechanical damage. Resistance change after the test shall be within \pm 20%.	Frequency range : 10 ~ 55 ~ 10 Hz/min Vibration amplitude : 1.5 mm Duration : 2 hours in each of XYZ directions (total : 6 hours)
15	Shock	No mechanical damage. Resistance change after the test shall be within \pm 20%.	Peak value : 490 m/s²(50G) Duration : 11 m sec. 6 aspects × 3 times (total : 18 times)
16	Thermal shock	No mechanical damage. Resistance change after the test shall be within \pm 20%.	-55 ± 3°C : 30 min. Room temperature : 2 ~ 3 min or less 125 ± 2°C : 30 min. Room temperature : 2 ~ 3 min or less Repeat above step for 10 cycles
17	Moisture resistance	No mechanical damage. Resistance change after the test shall be within $\pm20\%$.	Temperature : 85 ± 3°C Humidity : 85 ± 5% RH Duration : 1000 hours
18	Load life	No mechanical damage. Resistance change after the test shall be within \pm 20%.	Temperature : 85 ± 2°C Applied current : Rated current × 100% Duration : 1000 hours
19	Moisture resistance load	No mechanical damage. Resistance change after the test shall be within \pm 20%.	Temperature : 85 ± 2°C Humidity : 85 ± 5% RH Applied voltage : rated current × 100% Duration : 1000 h
20	Stability	No mechanical damage. Resistance change after the test shall be within $\pm~20\%$.	Temperature : 125 ± 2°C Duration : 1000 hours

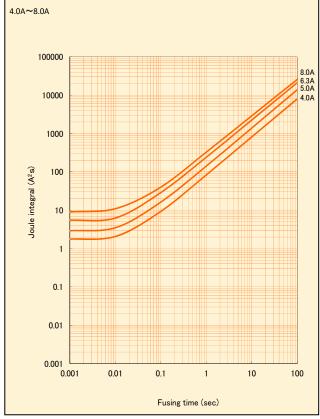
FUSING CHARACTERISTICS

I²T-T CHARACTERISTICS





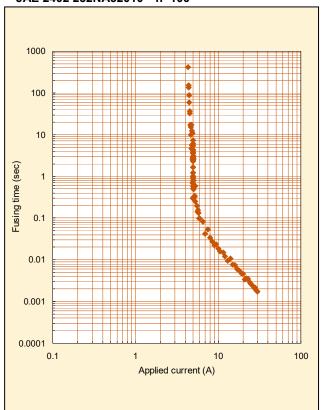




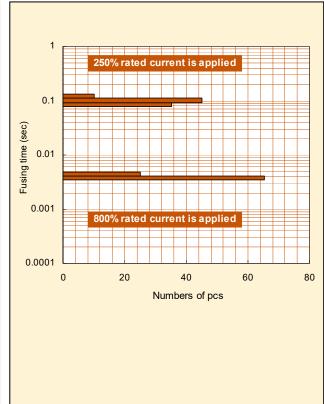
DISTRIBUTION OF FUSING CHARACTERISTICS

DISTRIBUTION OF FUSING TIME

JAE 2402 252NA52010 n=100



JAE 2402 252NA52010



DETERMINATION OF RATED VALUE AND SELECTION OF MICRO FUSE (TYPE JAE)

Determine the rated value of circuit protection element, and select the correct circuit protection element for your circuit. If you select the correct circuit protection element, safety of your circuit can be ensured.

How to determine the rated value of the circuit protection element is described below:

■Flow for fuse selection

1. Measurement of circuit values using actual device

Measure the circuit values, such as operating current of the circuit.

2. Calculation from operating current

From the obtained operating current and the category temperature, calculate the minimum rated value to determine the applicable fuse.

3. Calculation from overload current

From the obtained overload current, calculate the maximum rated value to determine the applicable fuse.

4. Calculation from inrush current

From the inrush current, calculate the minimum rated value to determine the applicable fuse.

5. Final determination of rated value

From the calculation results of steps 2 through 4, determine the rated value.

6. Operation check using actual device

After selecting the rating, confirm if the device works properly under the pre-determined conditions.

Fuse selection

1. Measurement of circuit values using actual device

Before determining the rated value of the fuse, preliminarily measure the following using the actual device.

1-1 Operating current

Using an oscilloscope or equivalents, measure the operating current of the circuit.

1-2 Overload current

Using an oscilloscope or equivalents, measure the overload current that needs to break the circuit.

1-3 Inrush current

Using an oscilloscope or equivalents, measure the inrush current of the circuit at power-on or power-off. In addition, determine the number of inrush current applied.

1-4 Category temperature

Measure the ambient temperature of the fuse circuit.

EXAMPLE TO SELECT RATINGS OF TYPE JAE

<Fuse selection>

Effective operating current : 1.2 A

Effective overload current : 6.0 A

Inrush current waveform : Fig. A

(Pulse width : 1 ms, Wave height : 6.0 A)

Numbers to withstand inrush current: 100,000 times

Category temperature: 85°C

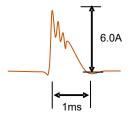


Fig. A: Inrush current waveform

2. Calculation from operating current

2-1 Measurement of operating current

Using an oscilloscope or equivalents, measure operating current (effective current) of the actual circuit.

Example: Effective operating current = 1.2 A

2-2 Derating

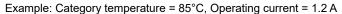
Temperature derating factor

Using Fig. B, find the temperature derating factor correspond to the temperature.

2Rated derating factor

Rated derating factor = 1.0 (Constant irrespective of temperature)

Use Formula 1 to calculate the rated current of the fuse to be used for the circuit. Rated current of fuse \geq Operating current / (① × ②) ... Formula 1



①Temperature derating factor = 0.76 (Refer to Fig. B.)

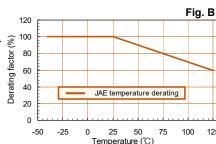
2Rated derating factor = 1.0 (Constant irrespective of temperature)

Calculation using Formula 1:

Rated current $\ge 1.2 / (0.76 \times 1.0) = 1.58 \text{ A}$

The above calculation result shows that the fuse with rated current of 1.58 A or more should be selected for this circuit.

Type JAE, with rated current of 1.6 A or more can be selected.



3. Calculation from overload current

3-1 Measurement of overload current

Using oscilloscope or equivalents, measure the overload current that needs to break the circuit.

Example: Effective overload current = 6.0 A

3-2 Calculation from overload current

Determine the rated current so that the overload current can be 2.5 times larger than the rated current.

Use Formula 2 to calculate the rated current of the fuse.

Rated current of fuse ≤ Overload current / 2.5 ... Formula 2

Example: Overload current = 6.0 A

Use Formula 2 to calculate the rated current.

Rated current \leq 6.0 / 2.5 = 2.4 A

The above calculation result shows that the fuse with rated current of 2.4 A or less should be selected for this circuit.

Type JAE, with rated current of 2.0 A or less can be selected.

4. Calculation from inrush current

4-1 Measurement of inrush current waveform

Using an oscilloscope or equivalent, measure the waveform of the inrush current of the actual circuit.

4-2 Creation of approximate waveform

Generally, the waveform of inrush current is complicated. For this reason, create the approximate waveform of inrush current as shown on Fig. C to simplify calculation.

4-3 Calculation of I2t of inrush current

Calculate I²t (Joule integral) of the approximate waveform.

The formula for this calculation depends on the approximate waveform. Refer to Table A.

Example : Pulse applied = 1 ms, Peak value = 6.0 A,

Approximate waveform = Triangular wave

Since the approximate waveform is a triangular wave, use the

following formula for calculation.

 I^2t of rush current = 1 / 3 × Im^2 × t ... Formula 3

(Im : Peak value, t : Pulse applying time)

Use Formula 3 to calculate I2t of the rush current :

 $I^2t = 1/3 \times 6 \times 6 \times 0.001 = 0.012$ (A²s)

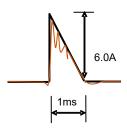


Fig. C : Inrush current waveform Red line : Actual measurement waveform Black line : Approximate waveform

JOULE-INTEGRAL VALUES FOR EACH WAVEFORM

Table A

Name	Waveform	I²t	Name	Waveform	I²t
Sine wave (1 cycle)	$0 \frac{1}{2} t$	1/2 I m²t Trapezoidal wave		O t ₁ t ₂ t ₃	$\frac{\frac{1}{3} \operatorname{Im}^{2} t_{1} + \operatorname{Im}^{2} (t_{2}-t_{1}) +}{\frac{1}{3} \operatorname{Im}^{2} (t_{3}-t_{2})}$
Sine wave (half cycle)	O t	$\frac{1}{2}$ I m ² t	Various wave 1	O t	$I_{1}I_{2}t + \frac{1}{3}(I_{1}-I_{2})^{2}t$
Triangular wave	O t Im	$\frac{1}{3}$ I m ² t	Various wave 2	0 t ₁ t ₂ t ₃	$\frac{1}{3} \frac{1_1^2 t_1 + \{I_1 I_2 + \frac{1}{3} (I_1 - I_2)^2\}}{(t_2 - t_1) + \frac{1}{3} I_2^2 (t_3 - t_2)}$
Rectangular wave	O t	I m² t	Charge/ discharge waveform	1 m i (t) = I m e ^{-t/τ} 0.368 I m	$\frac{1}{2}$ I m ² t

*Following formula is generally used for calculation of I²t as i(t) equal to current.

$$I^2t = \int_0^t i^2(t) dt$$

4-4 Search of load ratio

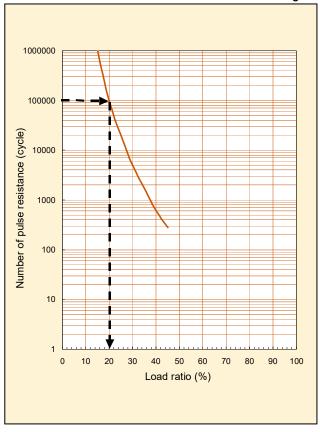
- ①Set up the number of cycles to withstand. (generally 100.000 times)
- ②Obtain the load ratio from Pulse resistance characteristics. (Fig. D)

Example: 100,000 times is required against inrush current applied.

The load ratio is 20% or less from Fig. D.

PULSE RESISTANCE CHARACTERISTICS

Fig. D



4–5 Calculation from Joule integral and load ratio Use Formula 4 to calculate the standard I²t for the fuse to be used.

Standard $\rm I^2t$ of fuse > ($\rm I^2t$ of inrush current / load ratio)Formula 4

Example : I^2t of pulse = 0.012 A²s, Pulse applied = 1 ms, Required load ratio = 20%

From Formula 4,

Standard I^2t of fuse > 0.012 / 0.2 = 0.06 (A²s)

The standard I²t of the fuse should be 0.06 (A²s) or more.

Since the rush pulse applied is 1 ms, obtain the intersection of 1 ms (horizontal axis) and $0.06\,\text{A}^2\text{s}$ (vertical axis) from Fig. E (refer to the arrow shown in Fig.E).

Select a fuse whose curve is above the intersection. Type JAE, with <u>rated current of 0.63 A or more</u> should be selected.

5. Final determination of rated value

Determine the rated current of the micro fuse. The rated current should meet all the calculation results.

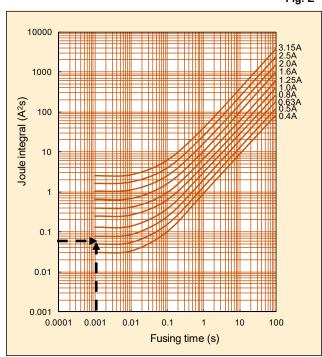
Example: 1.6 A and 2.0 A meet the all requirement.

6. Operation check using actual device

After selecting the rating, confirm if the device works properly under the pre-determined conditions.

JOULE INTEGRAL VS. FUSING TIME

Fig. E





Application Notes for Micro Fuse

Micro Fuse should be designated only after confirming operating conditions and Micro Fuse performance characteristics.

When determining the rated current, be sure to observe the following items:

- (1) Micro Fuse should always be operated below the rated current (the value considered in the temperature derating rate) and voltage specifications.
- (2) Micro Fuse should always be operated below the rated voltage.
- (3) Micro Fuse should be selected with correct rated value to be fused at overload current.
- (4) When Micro Fuse are used in inrush current applications, please confirm sufficiently inrush resistance of Micro Fuse.
- (5) Please do not apply the current exceeding the breaking current to Micro Fuse.
- (6) Use Micro Fuse under the condition of category temperature.
- (7) Micro Fuse should not be used in the primary power source.

Micro Fuse should be selected by determining the operating conditions that will occur after final assembly, or estimating potential abnormalities through cycle testing.

2. Assembly and Mounting

During the entire assembly process, observe Micro Fuse body temperature and the heating time specified in the performance table. In addition,

- (1) Mounting and adjusting with soldering irons are not recommended since temperature and time control is difficult.
- In case of emergency for using soldering irons, be sure to observe the conditions specified in the performance table.
- (2) Micro Fuse body should not contact a soldering iron directly.
- (3) Once Micro Fuse mounted on the board, they should never be remounted on boards or substrates.
- (4) During mounting, be careful not to apply any excessive mechanical stresses to the Micro Fuse.

3. Solvents

For cleaning of Micro Fuse, immersion in isopropyl alcohol for 90 seconds (at 20 ~ 30°C liquid temp.) will not be damaged.

If organic solvents will be used to Micro Fuse, be sure to preliminarily check that the solvent will not damage Micro Fuse.

4. Ultrasonic Cleaning

Ultrasonic cleaning is not recommended for Micro Fuse. This may cause damage to Micro Fuse such as broken terminals which results in electrical characteristics effects, etc. depending on the conditions.

If Ultrasonic cleaning process must be used, please evaluate the effects sufficiently before use.

5. Caution During Usage

- (1) Micro Fuse with electricity should never be touched. Micro Fuse with electricity may cause burning due to Micro Fuse high temperature. Also, in case of touching Micro Fuse without electricity, please check the safety temperature of Micro Fuse.
- (2) Protective eyeglasses should always be worn when performing fusing tests. However, there is a fear that Micro Fuse will explode during test. During fusing tests, please cover particles not to fly outward from the board or testing fixture. Caution is necessary during usage at all times.

6. Environmental Conditions

- (1) Micro Fuse should not be stored or operated in the presence of acids, or alkalis, or corrosive atmosphere.
- (2) Micro Fuse should not be vibrated, shocked, or pressed excessively.
- (3) Micro Fuse should not be operated in a flammable or explosive atmosphere.
- (4) Please do not use Micro fuse in the environment where dew condensation occurs. In case Micro fuse has to be used under the dew condensation condition, please apply moisture-proof coating over Micro fuse.

Covering Micro fuse with moisture-proof coating may affect electrical characteristics, please evaluate the effects sufficiently before use.

7. Emergency

In case of fire, smoking, or offensive odor during operation, please cut off the power in the circuit or pull the plug out.

- (1) Micro Fuse should not be stored in an environment with high temperature, low temperature, high humidity, condensation and dust and avoid direct sunlight or corrosive atmosphere such as H₂S(hydrogen sulfide) or SO₂(sulfur dioxide).
 - Direct sunlight may cause decolorization and deformation of the exterior and taping.
 - Also, solderability will be remarkably lower in high humidity.
- (2) If the products are stored for an extended period of time, please contact Matsuo Sales Department for recommendation. The longer storage term causes packages and tapings to worsen. If the products will be stored for longer term, please contact us for advice.
- (3) The products in taping, package, or box should not be given any kind of physical pressure. Deformation of taping or package may affect automatic mounting.
- (4) The plastic reel (made of PS) used for packaging the product is intended for use in ambient temperatures (5-35°C). To prevent issues during automated insertion due to reel deformation or other factors, please keep the reel away from direct sunlight and heat sources, and ensure it does not reach high temperatures (above 60°C), including during transportation.

When Micro Fuse are disposed of as waste or "scrap", they should be treated as "industrial waste". Micro Fuse contain various kinds of metals and resins.

10. Samples

Micro Fuse received as samples should not be used in any products or devices in the market. Samples are provided for a particular purpose such as configuration, confirmation of electrical characteristics, etc.



MATSUO ELECTRIC CO., LTD.

Please feel free to ask our Sales Department for more information on Micro Fuse.

Overseas Sales 5-3,3-Chome, Sennari-cho, Toyonaka-shi, Osaka 561-8558, Japan Tel: 06-6332-0883 Fax: 06-6332-0920 5-3,3-Chome,Sennari-cho,Toyonaka-shi,Osaka 561-8558,Japan Tel:06-6332-0871 Fax:06-6331-1386 Head office

https://www.ncc-matsuo.co.jp/

Specifications on this catalog are subject to change without prior notice. Please inquire of our Sales Department to confirm specifications prior to use.

市場	適用 用途	用途		推奨品種	推奨品種
III JA	分類	概要	代表的なアプリケーション例	チップタンタルコンデンサ	回路保護素子
高信頼度 機器	1	・高度な安全性や信頼性が要求される機器 ・製品の保守交換が不可能な機器、製品の故障が人命に直接かかわる、または、致命的なシステムダウンを引 き起こす可能性がある機器	宇宙開発機器関連(衛星、ロケット、人工衛星) ・航空・防衛システム ・原子力・火力・水力発電システム	267型Pシリーズ	該当なし
	2	 信頼性が重視される機器 製品の保守交換が極めて困難な機器や、製品の故障が人命に影響する、あるいは故障の 範囲が広範囲である機器 	自動車および鉄道・船舶等の輸送機器の車両制御 (エンジン制御、駆動制御、プレーキ制御) 新幹線・主要幹線の運行制御システム	267型Nシリーズ 271型Nシリーズ	JAG型Nシリーズ JAJ型Nシリーズ JAK型Nシリーズ JHC型Nシリーズ KAB型Nシリーズ KVA型Nシリーズ
車載・ 産業機器	3-A	車載用だが一般電装機器で車室内環境において使用される機器	・エアコン,カーナビ等の車室内搭載部品、 車載用通信機器		KAB型Mシリーズ
	3-B	・製品の保守交換が可能な機器や、製品の故障が人命に影響しないが故障による システムダウンの損失が大きく保全管理が要求される機器	・家庭用/ビル用等のセキュリティ管理システム ・工業用ロボットや工作機械等の制御機器	267型M.Eシリーズ 279型 281型M.Eシリーズ TCA型 TCD型	JHC型
汎用機器	4	・最先端技術を積極的に適用する小型・薄型品 ・製品の保守交換が可能な機器や、製品の故障によるシステムダウンが部分的な機器向けの 市場で広く使用されることを想定した製品	 スマートフォン、携帯電話、モバイルPC(タブレット)、電子辞書 デスクトップPC、ノートPC、ホームネットワーク アミューズメント機器(パチンコ、ゲーム機) 	251型Mシリーズ 267型Cシリーズ TCB型	JAE型、JAG型 JAJ型、JAK型 KAB型 KAB型Tシリーズ KVA型

Market	Application classification	Use		Recommendation Type	Recommendation Type
IVIAI KEL	by use	Outline	Typical example of application	Chip Tantalum Capacitors	Circuit Protection Components
High reliability apparatus	1	- Apparatus in which advanced safety and reliability are demanded Whether failure of the apparatus which cannot maintenance exchange products, and a product is direct for a human life, apparatus which changes or may cause a fatal system failure.	- Space development apparatus relation (Satellite, Rocket, Artificial Satellite) - Aviation and a defensive system - Atomic power, fire power, and a water-power generation system	Type 267 P Sereis	With no relevance
In-vehicle Industrial apparatus	2	- Apparatus in which reliability is important The apparatus in which maintenance exchange of a product is very difficult, and failure of a product influence a human life, or the range of failure is wide range.	- Vehicles control of transport machines, such as a car, and a railroad, a vessel (Engine control, drive control, brake control) - The operation control system of the Shinkansen and a main artery	Type 267 N Sereis Type 271 N Sereis	Type JAG N series Type JAJ N series Type JAK N series Type JAK N series Type HC N series Type KAB N series Type KAB N series
	3-A	- General electrical equipment designed for use in vehicles but used in the interior environment	Vehicle indoor loading parts, such as an air-conditioner and car navigation, and in-vehicle communication facility		Type KAB M series
	3-B	-Apparatus which can maintenance exchange products, and apparatus in which the loss of the system failure is large although failure of a product does not influence a human life, and maintenance engineering is demanded	- Security management system for home/buildings etc Control apparatus, such as Industrial use robots and a machine tool etc.	Type 267 M.E Sereis Type 279 Type 281 M.E Sereis Type TCA Type TCD	Туре ЈНС
Apparatus in general	4	The small size and the thin article which applies leading-edge technology positively The product supposing being used widely in the market for the apparatus which can maintenance exchange products, and apparatus with a partial system failure by failure of product.	-Smart phone. Mobile phone. Mobile PC (tablet), Electronic dictionary - Desktop PC, Notebook PC, Home network - Amusement apparatus (Pachinko,Game machine)	Type 251 M Series Type 267 C Series Type TCB	Type JAE, Type JAG Type JAJ, Type JAK Type KAB Type KAB T series Type KVA

テーピング数量・リール寸法

Taping Quantity And Carrier Tape Dimensions

チップタンタルコンデンサ **Chip Tantalum Capacitors**

定格: 251型Mシリーズ, TCB型 Type: 251 M Series, TCB

ケース記号 Case Code	ケースサイズ Case size	W (mm)	F (mm)	E (mm)	P ₁ (mm)	P ₂	P ₀ (mm)	ϕD_0 (mm)	包装数/リール(個) Quantity/Reel (pcs)	
0000 0000	0400 0.20	(11111)	(11111)	(11111)	(111111)	(11111)	(11111)	(11111)	φ180	
U	1.0×0.5				2.0±0.05			1.55±0.03	10,000	
М	1.6×0.8	0.010.3	8.0±0.3 3.5	0.2 2.5+0.05	3.5±0.05 1.75±0.1		2.0±0.05	4.0±0.1		
S	2.0×1.25	0.0±0.3	3 3.5±0.05 1.75±0.′	1.73±0.1	4.0±0.1	Z.U±0.05	4.0±0.1	1.5 ^{+0.1} ₀	3,000	
Α	3.2×1.6									

定格: 267型Mシリーズ, 267型Eシリーズ, 267型Pシリーズ, 271Nシリーズ

279型Mシリーズ, 281型Mシリーズ, 281型Eシリーズ Type: 267 M Series, 267 E Series, 267 P Series, 271 N Series

279 M Series, 281 M Series, 281 E Series

	279 W Jenes, 201 W Jenes, 201 L Jenes														
ケース記号 Case Code	ケースサイズ Case size	W (mm)	F (mm)	E (mm)	P ₁ (mm)	P ₂ (mm)	P ₀ (mm)	D ₀ (mm)	包装数/リ Quantity/f						
OddC OddC	Odde dize	(11111)	(111111)	(111111)	(111111)	(111111)	(111111)	(111111)	φ 180	ϕ 330					
Α	3.2×1.6	8.0±0.3	3.5±0.05	2 5+0 05	2 5 1 0 05	3 5 1 0 0 5	3 5 1 0 0 5	3 5+0 05		4.0±0.1				2,000	9,000
В	3.5×2.8	0.U±U.3		1.75±0.1	4.0±0.1	2.0±0.05	4.0±0.1 ϕ 1.5 ^{+0.1} ₀		2,000	8,000					
C3	6.0×3.2		5.5±0.05					500	3,000						
D3	7.3×4.4	12.0±0.3	5.7±0.05	1.5±0.1	8.0±0.1				2,500						
Н	7.3×4.4	12.0±0.3	5.7±0.1	1.510.1	1.5±0.1 0.0±0.1				500	1,500					
E	7.3×5.8		5.5±0.05	1.75±0.05					2,000						

定格:267型Nシリーズ、TCA型 Type: 267 N Series, TCA

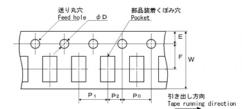
ケース記号 Case Code	ケースサイズ Case size	W (mm)	F (mm)	E (mm)	P ₁ (mm)	P ₂ (mm)	P ₀ (mm)	D ₀ (mm)	包装数/リール(個) Quantity/Reel (pcs)	
Case Code									φ 180	φ330
Α	3.2×1.6	8.0±0.3 12.0±0.3	3.5±0.05	1.75±0.1	4.0±0.1	2.0±0.05	4.0±0.1	φ 1.5 ^{+0.1} ₀	2,000	9,000
В	3.5×2.8									8,000
С	6.0×3.2		5.5±0.05		8.0±0.1				500	3,000
D	7.3×4.4		5.7±0.05 1.5±0.1	0.0±0.1				300	2,500	

回路保護素子

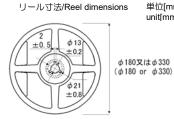
Circuit Protection Components

定格:JAE型、JAG型、JAG型Nシリーズ、JAJ型、JAJ型Nシリーズ、JAK型、JAK型Nシリーズ、JHC型Nシリーズ KAB型、KAB型Nシリーズ、KAB型Mシリーズ、KAB型Tシリーズ、KVA型、KVA型Nシリーズ Type:JAE, JAG, JAG N Series, JAJ, JAJ N Series, JAK, JAK N Series, JHC, JHC N Series KAB, KAB N Series, KAB M Series, KAB T Series, KVA, KVA N Series

IVAD, I	NAD, NAD IN Gelies, NAD IN Gelies, NAD I Gelies, NVA, NVA IN Gelies										
ケース記号 Case Code	ケースサイズ Case size	W (mm)	F (mm)	E (mm)	P ₁ (mm)	P ₂	P ₀ (mm)	D ₀ (mm)	包装数/リ Quantity/f	Iール(個) Reel (pcs)	
0400 0040	Odde dize	(11111)	(11111)	(111111)	(111111)	(111111)	(111111)	(111111)	ϕ 180	ϕ 330	
29	1.6×0.8		3.5±0.05	1.75±0.05	4.0±0.1	2.0±0.05		φ 1.55±0.03	5,000	-	
31	2.0×1.25	8.0±0.3								-	
52	3.2×1.6							φ1.5±0.1	2,000	-	
44E	7.3×5.8	12±0.3	5.5±005	1.75±0.1	8.0±0.1			φ 1.5 ^{+0.1} ₀	500	1,500	
59F	11.0×7.3	24±0.3	11.5±005		12.0±0.1				•	500	



テーピング寸法/Tape dimensions



単位[mm]

unit[mm]

チップタンタルコンデンサ テーピング形状記号

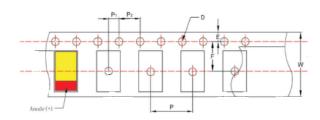
Chip Lantalu	m Capacitors	Tape code		
φ 180リール φ 180Reel		極性 Anode notation		
L		送り穴側 + Feed hole +		
R	N	送り穴側 — Feed hole —		

チップタンタルコンデンサ Chip Tantalum Capacitors

定格:TCD型 Type:TCD

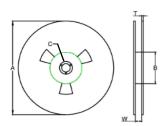
ケース記号 Case Code	ケースサイズ Case size	W (mm)	F (mm)	E (mm)	P (mm)	P ₁ (mm)	P ₂ (mm)	φD (mm)	包装数/リール(個) Quantity/Reel (pcs) <i>ф</i> 180
D	7.3×4.3×2.8	12±0.30	5.5±0.05	1.75±0.10	4±0.10	8±0.10	2±0.10	1.55±0.20	500

テーピング寸法/Tape dimensions



単位[mm] unit[mm]

リール寸法/Reel dimensions



リール Reel	テープ幅 Tape width	Α	В	С	W	Т
φ 180	12	178±2.00	50 min	13.0±0.50	12.4+1.5/-0	1.50±0.50